

IGBT Module

SK75GD126T

Preliminary Data

Features

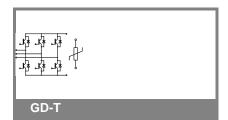
- One screw mounting module
- Fully compatible with SEMITOP®1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench IGBT technology
- CAL technology FWD
- Integrated NTC temperature sensor

Typical Applications*

- Inverter up to 42 kVA
- Typ. motor power 18,5 kW

Absolute Maximum Ratings $T_s = 25 ^{\circ}\text{C}$, unless otherwise specified						
Symbol	Conditions		Values	Units		
IGBT						
V_{CES}	T _j = 25 °C		1200	V		
I _C	T _j = 150 °C	T _s = 25 °C	88	Α		
		T _s = 70 °C	67	Α		
I _{CRM}	I _{CRM} = 2 x I _{Cnom}		140	Α		
V_{GES}			± 20	V		
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V	T _j = 125 °C	10	μs		
Inverse D	Diode			•		
I _F	T _j = 150 °C	$T_s = 25 ^{\circ}C$	91	Α		
		$T_s = 70 ^{\circ}C$	68	Α		
I _{FRM}	I _{FRM} = 2 x I _{Fnom}		150	Α		
Module						
I _{t(RMS)}				Α		
T_{vj}			-40 + 150	°C		
T _{stg}			-40 + 125	°C		
V _{isol}	AC, 1 min.		2500	V		

Characteristics $T_s = 25 ^{\circ}\text{C}$, unless otherwise spe					ecified	
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 3 \text{ mA}$		5	5,8	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C			0,0094	mA
		T _j = 125 °C				mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V	T _j = 25 °C			1200	nA
		T _j = 125 °C				nA
V _{CE0}		T _j = 25 °C		1	1,2	V
		T _j = 125 °C		0,9	1,1	V
r_{CE}	V _{GE} = 15 V	T _j = 25°C		10	13	mΩ
		T _j = 125°C		16	19	$\text{m}\Omega$
V _{CE(sat)}	I _{Cnom} = 75 A, V _{GE} = 15 V			1,7	2,1	V
		T _j = 125°C _{chiplev.}		2	2,4	V
C _{ies}				5		nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,26		nF
C _{res}				0,23		nF
$t_{d(on)}$				62		ns
t _r	$R_{Gon} = 8.2 \Omega$	V _{CC} = 600V		32		ns
Ė _{on}	di/dt = 1340 A/μs	I _C = 75A		11,3		mJ
t _{d(off)}	$R_{Goff} = 8.2 \Omega$	T _j = 125 °C		514		ns
t _f	di/dt = 1340 A/µs	V _{GE} = -7/+15 V		90		ns
E _{off}				10		mJ
$R_{th(j-s)}$	per IGBT			0,5		K/W





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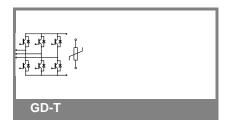
Typical Applications*

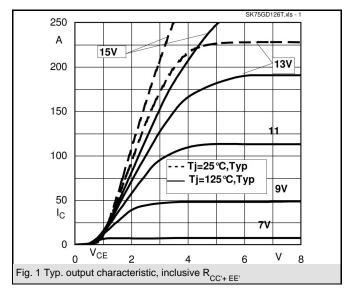
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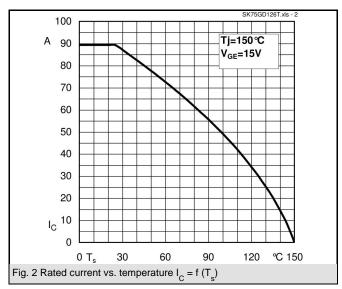
Characteristics							
Symbol	Conditions	İ	min.	typ.	max.	Units	
Inverse Diode							
$V_F = V_{EC}$	I_{Fnom} = 75 A; V_{GE} = 0 V	$T_j = 25 ^{\circ}C_{chiplev.}$		1,46		V	
		T _j = 125 °C _{chiplev.}		1,4		V	
V _{F0}		T _j = 25 °C		1,05		V	
		T _j = 125 °C		0,95		V	
r _F		T _j = 25 °C		5,5		mΩ	
		T _j = 125 °C		6		$m\Omega$	
I _{RRM}	I _F = 75 A	T _j = 125 °C		70		Α	
Q_{rr}	di/dt = 1340 A/µs			20		μC	
E _{rr}	V _{CC} = 600V			6		mJ	
R _{th(j-s)D}	per diode			0,7		K/W	
M_s	to heat sink		2,5		2,75	Nm	
w				60		g	
Temperat	ure sensor						
R ₁₀₀	T_s =100°C (R_{25} =5kΩ)			493±5%		Ω	

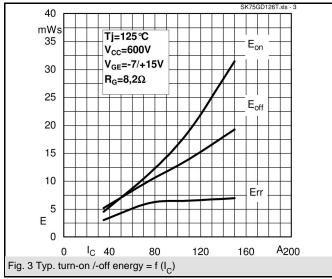
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

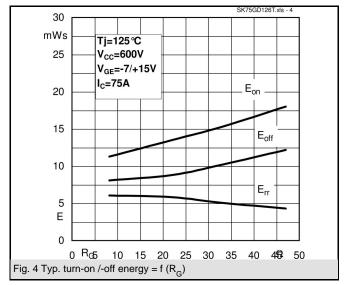
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

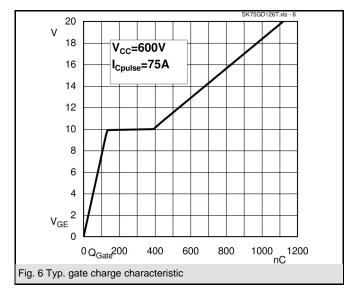


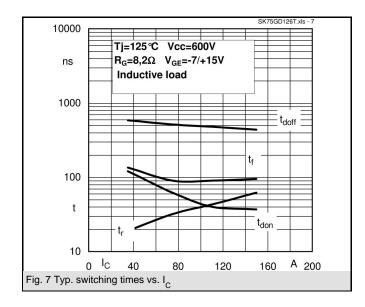


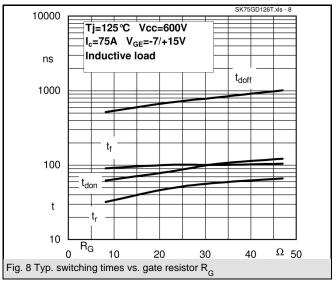


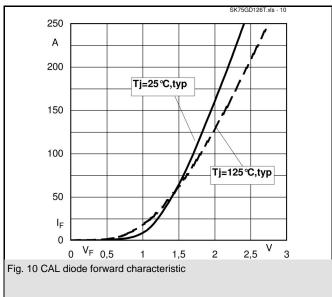


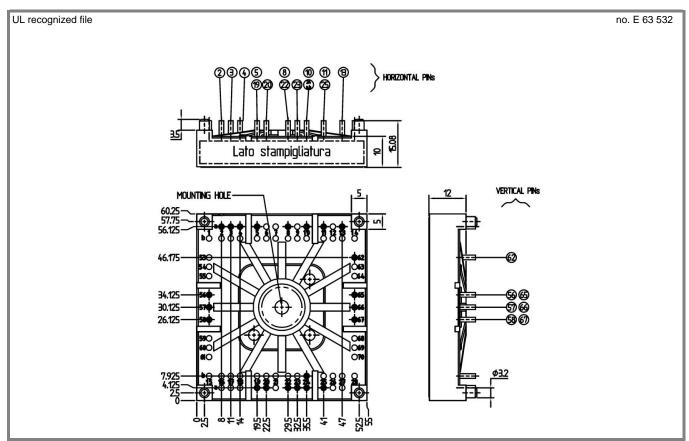












Case T74 (Suggested hole diameter for the solder pins in the circuit board: 2mm. Suggested hole diameter for the mounting pins in the circuit board: 3,6mm)

